



NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
- 1.2 CONTACT: COPPER ALLOY
- 1.3 FIT NAIL: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

- GOLD PLATING ON CONTACT AREA.
- 100~200u" MATTE TIN PLATING ON SOLDER TAILS.
- 50~100u" NICKEL UNDERPLATING OVERALL.

2.2 FIT NAIL:

- 100~200u" MATTE TIN PLATING ON SOLDER TAILS.
- 50~100u" NICKEL UNDERPLATING OVERALL.

3. REFLOW SOLDER CAPABLE TO 260°C ,PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-52701-XXXXX-XXX

5. PACKAGE PLS. REFER TO 52704-XXXXX

6. PART NUMBER

52704-XXX X X-XXX

NO OF CKT ——— TYPE
 098 ——— 001:NONE
 164 ——— PLATING
 D: 30u" GOLD PLATING

PACKING

- 0:TAPE & REEL
- 2:TRAY
- 4:TAPE & REEL WITH MYLAR
- 6:TRAY WITH MYLAR

| CONNECTOR LINK WIDTH | CKT | DIM.A | DIM.B | DIM.C | DIM.D | DIM.E | DIM.F | DIM.G |
|----------------------|-----|-------|-------|-------|-------|-------|-------|-------|
| X8 | 98 | 38.65 | 56.00 | 40.15 | 58.00 | 37.00 | 39.15 | 52 |
| X16 | 164 | 71.65 | 89.00 | 73.15 | 91.00 | 70.00 | 72.15 | 85 |

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| QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓢ | DRAWN BY Lin, Chia Ann | DATE 21/06/23 | |
| | CHECKED BY Lee, I Hung | DATE 21/06/23 | |
| GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2° | APPROVED BY Wang, Chun Sheng | DATE 21/06/23 | TITLE PCIE GEN4 EDGE CARD SOCKET CONN. SMT D/R S/T TYPE |
| | UNITS mm | | SIZE A4 |
| SCALE 2:1 | SHEET NO. 1 OF 2 | REV C | PART NO. SEE NOTES |

